

REMARKS

Favorable reconsideration of this application is requested in view of the above amendments and the following remarks. Claims 1 and 7 are amended. The revisions to claims 1 and 7 are supported, for example, at Figure 1, and at page 7, lines 4-19 in the specification. Claim 12 is added. Support for new claim 12 can be found, for example, at Figure 1, and at page 7, lines 4-19 in the specification.

Claims 1-2, 4-10, and 12 are pending, with claims 1, 7, and 12 being independent.

Claim rejections - 35 U.S.C. § 103

Claims 1, 4, and 6 stand rejected as being unpatentable over U.S. Patent No. 6,281,568 (Glenn) in view of U.S. Patent No. 5,986,333 (Nakamura). Applicant respectfully traverses this rejection.

Claim 1 is directed to a semiconductor device. The die-pad is formed with at least one slit that is located between a peripheral edge of the die-pad and a semiconductor chip. The at least one slit is formed along a side of the chip and extends from a first position that is closer to the first corner of the chip to a second position that is closer to the second corner of the chip.

Glenn is directed to a package for an integrated circuit device. However, Glenn does not teach or suggest at least the feature of a die-pad being formed with at least one slit that is located between a peripheral edge of the die-pad and a semiconductor chip, and that extends in the manner recited in claim 1.

Nakamura does not remedy the deficiencies of Glenn. Nakamura discloses a die-pad with V- or U-shaped slits formed a corner of the die-pad. See, for example, Figure 3 of Nakamura. These slits, however, are not formed along a side of the chip. Nor do they extend from a first position that is closer to the first corner of the chip to a second position that is closer to the second corner of the chip.

Accordingly, Applicant submits that claim 1 is allowable over the cited references. Applicant respectfully requests that the rejection of claim 1 be withdrawn.

Claims 4 and 6 depend from claim 1, and are also believed allowable for at least the reason that they are dependent upon an allowable base claim.

Claim 2 stands rejected as being unpatentable over Glenn in view of Nakamura and U.S. Patent No. 5,410,182 (Kurafuchi). Applicant respectfully traverses this rejection.

Claim 2 depends from claim 1 and is believed allowable for at least the reason that it is dependent upon an allowable base claim. Kurafuchi does not remedy the deficiencies of Glenn and Nakamura. Accordingly, Applicant respectfully requests that the rejection of claim 2 be withdrawn. Applicant does not concede the correctness of this rejection.

Claim 5 stands rejected as being unpatentable over Glenn in view of Nakamura and U.S. Patent No. 6,566,168 (Gang). Applicant respectfully traverses this rejection.

Claim 5 depends from claim 1 and is believed allowable for at least the reason that it is dependent upon an allowable base claim. Gang does not remedy the deficiencies of Glenn and Nakamura. Accordingly, Applicant respectfully requests that the rejection of claim 5 be withdrawn. Applicant does not concede the correctness of this rejection.

Claims 7-10 stand rejected as being unpatentable over Glenn in view of Gang and Nakamura. Applicant respectfully traverses this rejection.

Claim 7 is directed to a semiconductor device. At least one slit is located between the peripheral edge of a die-pad and a semiconductor chip. The at least one slit is formed along a side of the chip and extends from a first position that is closer to the first corner of the chip to a second position that is closer to the second corner of the chip.

As noted above with respect to claim 1, neither Glenn nor Nakamura teach or suggest at least these features. Gang does not remedy the deficiencies of Glenn and Nakamura.

Accordingly, Applicant respectfully submits that claim 7 is allowable over the cited references.

Claims 8-10 depend from claim 7, and are also believed allowable for at least the reason that they are dependent upon an allowable base claim. Applicant respectfully requests that the rejection of claims 8-10 be withdrawn. Applicant does not concede the correctness of this rejection.

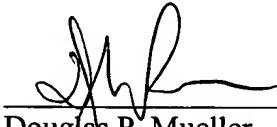
Newly presented claim 12 is also believed allowable over the cited references. Claim 12 is directed to a semiconductor device. A plurality of slits is located between a peripheral edge of the die-pad and the semiconductor chip. The slits face the first side and second side, respectively, of the semiconductor chip, and are discontinuous with each other at the corner of the chip. Applicant respectfully submits that the cited references do not teach or suggest at least these features. Accordingly, Applicant respectfully submits that claim 12 is in condition for allowance.

In view of the above, favorable reconsideration in the form of a notice of allowance is requested.

Respectfully submitted,

MERCHANT & GOULD P.C.
P.O. Box 2903
Minneapolis, Minnesota 55402-0903
(612) 332-5300

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Douglas P. Mueller
Reg. No. 30,300
DPM:DTL